

# SMT power inductors

Size 6.3 x 6.3 x 2.5 (mm)

Series/Type: B82462G2

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product		Deadline Last Orders	Last Shipments
B82462G2*		2012-03-16	2012-09-28	2013-03-29

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

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B82462G2

#### **SMT** power inductors

Size 6.3 x 6.3 x 2.5 (mm)

## **SMD**

Rated inductance 0.82 ... 330 µH Rated current 0.22 ... 3.25 A

#### Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding welded to terminals

#### **Features**

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

## **Applications**

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics

#### **Terminals**

- Base material CuSn6
- Layer composition Ag, Sn (lead-free)¹)
- Electro-plated

#### Marking

- Marking on component:
   Manufacturer, L value (nH, coded),
   L tolerance (coded), manufacturing date (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

#### Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 2500 pcs./reel





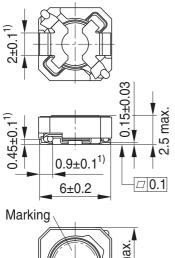
<sup>1)</sup> Ni-barrier-plated terminals on request (B82462G2\*50).

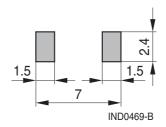
B82462G2

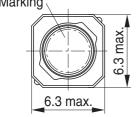
## Size 6.3 x 6.3 x 2.5 (mm)

# **SMD**

#### Dimensional drawing and layout recommendation







1) Soldering area

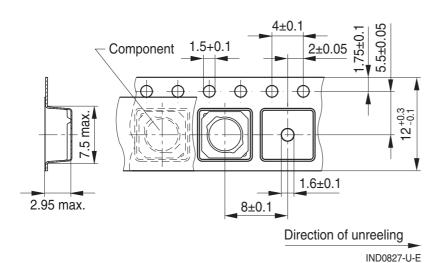
IND0470-D-E

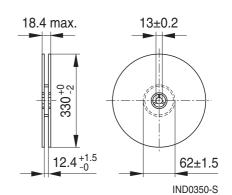
#### Dimensions in mm

Reel

## Taping and packing

Blister tape





Dimensions in mm



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# Technical data and measuring conditions

Rated inductance L <sub>R</sub>	Measured with impedance analyzer Agilent 4294A at frequency $f_L$ , 0.1 V, +20 $^{\circ}\text{C}$			
Rated temperature T <sub>R</sub>	+85 °C			
Rated current I <sub>R</sub>	Max. permissible DC with temperature increase of $\leq$ 40 K at rated temperature			
Saturation current I <sub>sat</sub>	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%			
DC resistance R <sub>max</sub>	Measured at +20 °C			
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: $+(245 \pm 5)$ °C, $(5 \pm 0.3)$ s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)			
Resistance to soldering heat	+260 °C, 40 s as referenced in JEDEC J-STD 020D			
Climatic category	55/150/56 (to IEC 60068-1)			
Storage conditions	Mounted: -55 °C +150 °C Packaged: -25 °C +40 °C, ≤75% RH			
Weight	Approx. 1.5 g			



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# SMD

# **Characteristics and ordering codes**

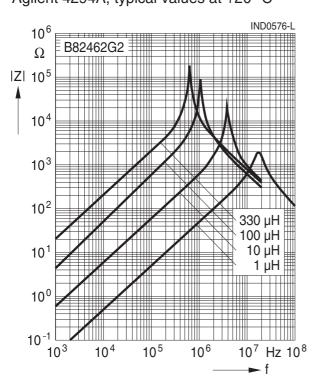
L <sub>R</sub>	Tolerance	$f_{L}$	I <sub>R</sub>	I <sub>sat</sub>	R <sub>max</sub>	Ordering code
μΗ		MHz	Α	A	Ω	
0.82	±20% ≙ M	0.1	3.25	4.40	0.017	B82462G2821M000
1.0		0.1	3.25	4.25	0.017	B82462G2102M000
1.2		0.1	3.10	3.60	0.019	B82462G2122M000
1.8		0.1	2.75	3.00	0.022	B82462G2182M000
2.2		0.1	2.30	2.55	0.032	B82462G2222M000
3.3		0.1	2.00	2.05	0.040	B82462G2332M000
4.7		0.1	1.60	1.80	0.061	B82462G2472M000
6.8		0.1	1.45	1.48	0.078	B82462G2682M000
10		0.1	1.25	1.28	0.106	B82462G2103M000
15		0.1	1.02	1.02	0.160	B82462G2153M000
22		0.1	0.83	0.83	0.245	B82462G2223M000
33		0.1	0.68	0.68	0.345	B82462G2333M000
47		0.1	0.62	0.56	0.420	B82462G2473M000
68		0.1	0.48	0.47	0.635	B82462G2683M000
100		0.1	0.41	0.41	0.950	B82462G2104M000
150		0.1	0.33	0.31	1.480	B82462G2154M000
220		0.1	0.28	0.26	2.10	B82462G2224M000
330		0.1	0.22	0.20	3.25	B82462G2334M000

<sup>1)</sup> For Ni-barrier-plated terminals replace the last two digits "00" by "50".

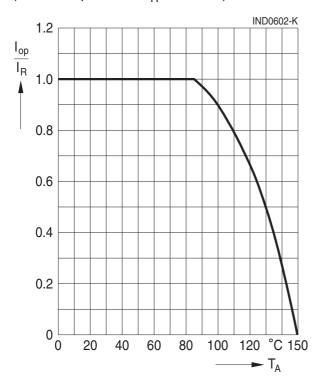


Size 6.3 x 6.3 x 2.5 (mm)

# Impedance |Z| versus frequency f measured with impedance analyzer Agilent 4294A, typical values at +20 °C

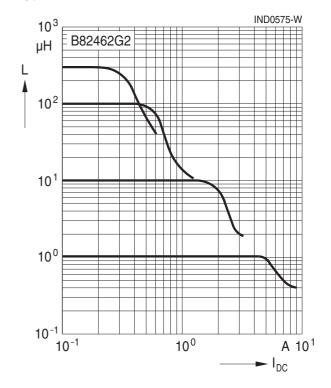


# Current derating $I_{op}/I_R$ versus ambient temperature TA (rated temperature T<sub>R</sub> = +85 °C)



# **SMD**

# Inductance L versus DC load current $I_{DC}$ measured with LCR meter Agilent 4275A, typical values at +20 °C





#### **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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